

RECOMMENDED PCB LAYOUT  
TOLERANCE: ± 0.05

NOTE:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC,COLOR:BLACK  
TERMINAL: BeCu-TM04,THICKNESS:0.15mm

2.FINISH:

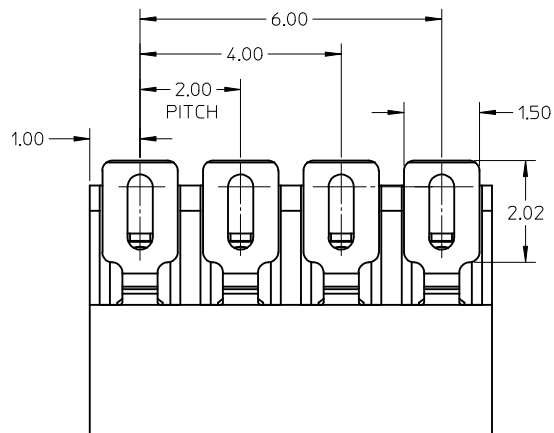
CONTACT AREA: 0.75 MICRON GOLD MIN OVER 1.25 MICRON NICKEL MIN.  
SOLDER AREA: GOLD FLASH (0.075-0.125 MICRON) OVER 1.25 MICRON NICKEL MIN.  
REST AREA: 1.25 MICRON NICKEL MIN.

3.COPLANARITY: 0.08 MAX AMONG THESE SOLDER TAILS.

4.PRODUCT SPECIFICATION: PS-47420-001

5.WORKING RANGE: 1.55 - 1.95MM COUNTED FROM TOP OF PCB

6.NORMAL FORCE AT 0.8 DEFLECTION IS 110±25 GRAMS.



NEW RELEASE EC NO: SH2007-0482 DRW: LHSN 2007/01/18 CHKD: XU XIANG 2007/01/19 APPR: JINCHEN 2007/01/19	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH	DRAWN BY LHSN	DATE 2006/02/21	TITLE 2.0MM PITCH 4 CIRCUITS 0.7MM CONTACT WIDTH BATTERY CONNECTOR
		4 PLACES	± ---	± ---	CHECKED BY	DATE	MOLEX INCORPORATED
		3 PLACES	± ---	± ---	APPROVED BY	DATE	
2 PLACES	± 0.15	± ---	MATERIAL NO. 474200001		DOCUMENT NO. SD-47420-001	SHEET NO. 1 OF 1	
1 PLACE	± 0.15	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		